

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1773	correct\$3 and bump and block and (plurality or plurals)and(wafer\$1 or semiconductor\$1 or chip\$1 or integrated adj circuit or IC)and(inclinat\$3 or shift\$3 or slope or skew)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 14:55
L3	45	1 and (ccd or camera or detector\$1 or sensor\$1)and scann\$3 near3(sprial or serpentine or circle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 14:58
L5	0	3 and wafer\$1 near3 turn\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 14:59
L6	40	3 and (detect\$3 or determine)and mark\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 15:00
L7	39	6 and coordinat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 15:01
L8	39	7 and inspect\$3 and recognit\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 15:01



Welcome to IEEE Xplore®

- Home
- What Can I Access?
- Log-out

Tables of Contents

- Journals & Magazines
- Conference Proceedings
- Standards

Search

- By Author
- Basic
- Advanced
- CrossRef

Member Services

- Join IEEE
- Establish IEEE Web Account
- Access the IEEE Member Digital Library

IEEE Enterprise

- Access the IEEE Enterprise File Cabinet

Try our New Full-text Search Prototype **GO**

Help

- 1) Enter a single keyword, phrase, or Boolean expression.
Example: acoustic imaging (means the phrase acoustic imaging plus any stem variations)
- 2) Limit your search by using search operators and field codes, if desired.
Example: optical <and> (fiber <or> fibre) <in> ti
- 3) Limit the results by selecting Search Options.
- 4) Click Search. See [Search Examples](#)

bump and block and (wafer or semiconductor or chip or substrate)



Start Search **Clear**

Note: This function returns plural and suffixed forms of the keyword(s).

Search operators: <and> <or> <not> <in> [More](#)

Field codes: au (author), ti (title), ab (abstract), jn (publication name), de (index term) [More](#)

Search Options:

Select publication types:

- IEEE Journals
- IEE Journals
- IEEE Conference proceedings
- IEE Conference proceedings
- IEEE Standards

Select years to search:

From year: **All** **▼** to **Present**

Organize search results by:

Sort by: **Relevance** **▼**
In: **Descending** order
List **15** **▼** Results per page



» See



Welcome to IEEE Xplore®

- Home
- What Can I Access?
- Log-out

Tables of Contents

- Journals & Magazines
- Conference Proceedings
- Standards

Search

- By Author
- Basic
- Advanced
- CrossRef

Member Services

- Join IEEE
- Establish IEEE Web Account
- Access the IEEE Member Digital Library

IEEE's Enterprise

- Access the IEEE Enterprise File Cabinet

Print Format

Your search matched **15** of **1105713** documents.
A maximum of **500** results are displayed, **15** to a page, sorted by **Relevance Descending** order.

Refine This Search:

You may refine your search by editing the current search expression or enter a new one in the text box.

bump and block and (wafer or semiconductor or chip or

Check to search within this result set

Results Key:

JNL = Journal or Magazine **CNF** = Conference **STD** = Standard

1 Applications of newly developed positive photosensitive block co-polyimides to CSPs

Matsumoto, S.; Xing Zhou Jin; Fukushima, T.; Miyamura, M.; Itatani, H.; Electronics Packaging Technology Conference, 2000. (EPTC 2000). Proceeding 3rd, 5-7 Dec 2000

Pages: 367 - 372

[\[Abstract\]](#) [\[PDF Full-Text \(720 KB\)\]](#) **IEEE CNF**

2 An adaptive neuro/fuzzy CMOS chip

Salam, F.M.A.; Erten, G.;

Circuits and Systems, 1995. ISCAS '95., 1995 IEEE International Symposium on, Volume: 3, 28 April-3 May 1995

Pages: 2329 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(104 KB\)\]](#) **IEEE CNF**

3 Micromachined silicon conformal packaging for millimeter wave systems applications

Katehi, L.P.B.; Kihm, R.T.;

Electrical Performance of Electronic Packaging, 1998. IEEE 7th topical Meeting on, 26-28 Oct. 1998

Pages: 247

[\[Abstract\]](#) [\[PDF Full-Text \(44 KB\)\]](#) **IEEE CNF**

4 Radiation tolerance of prototype BTeV pixel detector readout chips

Chioldini, G.; Appel, J.A.; Cardoso, G.; Christian, D.C.; Coluccia, M.R.; Hall, B.

Hoff, J.; Kwan, S.W.; Mekkaoui, A.; Yarema, R.; Zimmerman, S.; Uplegger, L.

Nuclear Science, IEEE Transactions on, Volume: 49, Issue: 6, Dec. 2002

Pages:2895 - 2901

[\[Abstract\]](#) [\[PDF Full-Text \(460 KB\)\]](#) [IEEE JNL](#)

5 Heterogeneous integration of OE arrays with Si electronics and microoptics

Yue Liu;

Advanced Packaging, IEEE Transactions on [see also Components, Packaging Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on] , Volume: 25 , Issue: 1 , Feb. 2002

Pages:43 - 49

[\[Abstract\]](#) [\[PDF Full-Text \(677 KB\)\]](#) [IEEE JNL](#)

6 Competitive learning with floating-gate circuits

Hsu, D.; Figueroa, M.; Diorio, C.;

Neural Networks, IEEE Transactions on , Volume: 13 , Issue: 3 , May 2002

Pages:732 - 744

[\[Abstract\]](#) [\[PDF Full-Text \(423 KB\)\]](#) [IEEE JNL](#)

7 GaInP/GaAs HBTs for high-speed integrated circuit applications

Ho, W.J.; Chang, M.F.; Sailer, A.; Zampardi, P.; Deakin, D.; McDermott, B.; Pierson, R.; Higgins, J.A.; Waldrop, J.;

Electron Device Letters, IEEE , Volume: 14 , Issue: 12 , Dec. 1993

Pages:572 - 574

[\[Abstract\]](#) [\[PDF Full-Text \(208 KB\)\]](#) [IEEE JNL](#)

8 GaInP/GaAs HBT's for high-speed integrated circuit applications

Ho, W.J.; Chang, M.F.; Sailer, A.; Zampardi, P.; Deakin, D.; McDermott, B.; Pierson, R.; Higgins, J.A.;

Electron Devices, IEEE Transactions on , Volume: 40 , Issue: 11 , Nov 1993

Pages:2113 - 2114

[\[Abstract\]](#) [\[PDF Full-Text \(220 KB\)\]](#) [IEEE JNL](#)

9 Heterogeneous integration of InP/InGaAsP MQW thin film edge emi lasers and polymer waveguides

Hung-Fei Kuo; Sang-Yeon Cho; Jokerst, N.M.;

Electronic Components and Technology, 2004. ECTC '04. Proceedings , Volum 2 , 1-4 June 2004

Pages:1537 - 1541 Vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(456 KB\)\]](#) [IEEE CNF](#)

10 Equipment for placement and bonding

Rusander, F.;

The First IEEE International Symposium on Polymeric Electronics Packaging , Oct. 1997

Pages:259 - 264

[\[Abstract\]](#) [\[PDF Full-Text \(480 KB\)\]](#) [IEEE CNF](#)

11 Materials and mechanics issues in flip-chip organic packaging

Wu, T.Y.; Tsukada, Y.; Chen, W.T.;

Electronic Components and Technology Conference, 1996. Proceedings., 46th
31 May 1996

Pages:524 - 534

[\[Abstract\]](#) [\[PDF Full-Text \(1140 KB\)\]](#) [IEEE CNF](#)

12 The module controller chip (MCC) of the ATLAS pixel detector

Beccherle, R.;

Nuclear Science Symposium, 1998. Conference Record. 1998 IEEE , Volume:
14 Nov. 1998

Pages:69 - 74 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(576 KB\)\]](#) [IEEE CNF](#)

**13 Development of ball bump forming technology using solder paste a
new simplified CSP**

Fujino, J.; Takaki, S.; Hayashi, K.; Izuta, G.; Hirota, J.;

Electronic Components and Technology Conference, 1998. 48th IEEE , 25-28 I
1998

Pages:442 - 447

[\[Abstract\]](#) [\[PDF Full-Text \(828 KB\)\]](#) [IEEE CNF](#)

14 A 93 MHz, X86 microprocessor with on-chip L2 cache controller

*Draper, D.; Crowley, M.; Doppalapudi, U.; McFarland, H.; Mo, B.; Partovi, H.;
Puziol, D.; Scherer, A.; Tosaya, E.; Van Dyke, K.; Vuong, A.; Widigen, L.; Yip,
Yu, S.; Roth, D.;*

Solid-State Circuits Conference, 1995. Digest of Technical Papers. 42nd ISSCC
1995 IEEE International , 15-17 Feb. 1995

Pages:172 - 173, 360

[\[Abstract\]](#) [\[PDF Full-Text \(756 KB\)\]](#) [IEEE CNF](#)

15 A wafer-scale FFT processor featuring a repeatable building block

Yamashita, K.; Kanasugi, A.; Hijiya, S.; Goto, G.;

Wafer Scale Integration, 1989. Proceedings., [1st] International Conference o
5 Jan. 1989

Pages:299 - 307

[\[Abstract\]](#) [\[PDF Full-Text \(396 KB\)\]](#) [IEEE CNF](#)
